

**In the Abstract**

Please replace the abstract with the following abstract:

A method of making a multi-layered interconnect structure. First and second electrically conductive members are formed on the first and second dielectric layers, respectively. The dielectric layers are formed on opposing surfaces of a thermally conductive layer. A first and second electrically conductive layer is formed within the first dielectric layer. The second electrically conductive layer includes shielded signal conductors and is positioned between the first electrically conductive layer and the thermally conductive layer. A plated through hole (PTH) formed through the interconnect structure is electrically connected to one of the first and second electrically conductive members and to one of the shielded signal conductors. A third dielectric layer, formed on the first dielectric layer and on portions of the first electrically conductive members, substantially overlies the PTH and includes a high density interconnect layer for providing an electrical path from an electronic device to the shielded signal conductors.